




PCN Number:	20140903000			PCN Date:	09/03/2014										
Title:	Qualification of TIPI a new Assembly Site for Select Devices in the PBGA Package														
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services										
Proposed 1st Ship Date:	03/03/2015		Estimated Sample Availability:	Date provided at sample request											
Change Type:															
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site										
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material										
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process										
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site										
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials										
				<input type="checkbox"/>	Wafer Fab Process										
PCN Details															
Description of Change:															
Qualification of TIPI as a new Assembly Site for Select Devices in the PBGA Package. Assembly differences are as follows:															
BGA Package Type	StatsChipPac Korea (CPK)			TI Philippines (TIPI)											
	Mount Compound	Mold Compound	Wire Type (mil)	Mount Compound	Mold Compound	Wire Type (mil)									
GDP ZDP	R008-0022A	R005-B057	1.0 Au	4205412	4206745/ 4208515	0.96 Au									
Reason for Change:															
StatsChipPac Korea informed TI they will no longer be able to manufacture at this location.															
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):															
None															
Changes to product identification resulting from this PCN:															
Sample Product Shipping Label (not actual product label)															
<table border="1"> <tr> <td colspan="3">Assembly Site</td> </tr> <tr> <td>StatsChipPac Korea (CPK)</td> <td>Assembly Site Origin (22L)</td> <td>ASO: CPA</td> </tr> <tr> <td>TI Philippines (TIPI)</td> <td>Assembly Site Origin (22L)</td> <td>ASO: PHI</td> </tr> </table>							Assembly Site			StatsChipPac Korea (CPK)	Assembly Site Origin (22L)	ASO: CPA	TI Philippines (TIPI)	Assembly Site Origin (22L)	ASO: PHI
Assembly Site															
StatsChipPac Korea (CPK)	Assembly Site Origin (22L)	ASO: CPA													
TI Philippines (TIPI)	Assembly Site Origin (22L)	ASO: PHI													
 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2Q:															
<table border="1"> <tr> <td>MSL 2 /260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 /235C/UNLIM</td> <td>03/29/04</td> </tr> </table>		MSL 2 /260C/1 YEAR	SEAL DT	MSL 1 /235C/UNLIM	03/29/04	OPT: ITEM: 39 LBL: 5A (L)T0:1750		(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS							
MSL 2 /260C/1 YEAR	SEAL DT														
MSL 1 /235C/UNLIM	03/29/04														
Assembly Site Codes: CPK = 8, TIPI = W															

Product Affected:			
SM32C6711DGDPA16EP	SM32C6713BGDPA20EP	V62/04603-02XA	V62/04753-04YA
SM32C6711DGDPI20EP	SM32C6713BGDPM30EP	V62/04603-03XA	V62/04753-16YA
SM32C6712DGDPA16EP	SM32C6713BGDPS20EP	V62/04603-04XA	V62/04754-03YA

Qualification Data/Plan

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Data Approved: **September, 2014**

Qual Vehicle # 1: D610A3BGDPA225 (MSL3-220C)

Package Construction Details

Assembly Site:	TIPI	Mold Compound:	4208515
# Pins-Designator, Family:	272-GDP, PBGA	Mount Compound:	4205412
Solder Ball Composition:	SnPb	Bond Wire:	0.80 Mil Dia., Cu

Qualification: Plan **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
Electrical Characterization	Per Datasheet Specifications	Pass	Pass	Pass
**High Temp Operating Life	125C (1000 Hrs)	77/0	77/0	77/0
** Biased Temp Humidity	85C/85%RH (1000 Hrs)	26/0	26/0	26/0
**Unbiased HAST	110C/85%RH (264 Hrs)	77/0	77/0	77/0
**T/C -55C/125C	-55C/125C (700 Cyc)	77/0	77/0	77/0
** High Temp Storage Bake	150C (1000 Hrs)	45/0	45/0	45/0

Notes ** - Preconditioning sequence: Level 3-220C.

Qualification Data Approved: **September, 2014**

Qual Vehicle # 2: D610A3BGDPA225 (MSL3-220C)

Package Construction Details

Assembly Site:	TIPI	Mold Compound:	4208515
# Pins-Designator, Family:	272-GDP, PBGA	Mount Compound:	4205412
Solder Ball Composition:	SnPb	Bond Wire:	0.96 Mil Dia., Au

Qualification: Plan **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
Electrical Characterization	Per Datasheet Specifications	Pass	Pass	Pass
**Unbiased HAST	110C/85%RH (264 Hrs)	77/0	77/0	77/0
**T/C -55C/125C	-55C/125C (700 Cyc)	77/0	77/0	77/0

Notes ** - Preconditioning sequence: Level 3-220C.

Qualification Data Approved:		September, 2014		
Qual Vehicle # 3: D610A3BZDPA225 (MSL4-260C)				
Package Construction Details				
Assembly Site:	TIPI	Mold Compound:	4208515	
# Pins-Designator, Family:	272-ZDP, PBGA	Mount Compound:	4205412	
Solder Ball Composition:	SnAgCu	Bond Wire:	0.80 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
Electrical Characterization	Per datasheet Specifications	Pass	Pass	Pass
**Unbiased HAST	110C/85%RH (264 Hrs)	77/0	77/0	77/0
**T/C -55C/125C	-55C/125C (700 Cyc)	77/0	77/0	77/0
Notes ** - Preconditioning sequence: Level 4-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com